

Y. Suetsugu and K.Kanazawa, KEKB Vac Group

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- Experiments (2003~)
 - Structure of Beam Duct
 - Surfaces with a Low SEY
- Summary





• Studies on ECI at KEK B-factory (KEKB)

Using positron ring (LER)

- E = 3.5 GeV, I = max.1.7 A, 1.2 mA/bunch (1.2x10⁻⁸ C)
- Usually ~1400 bunches, 6 ~ 8 ns bunch spaces
- Beam duct : ϕ 94 mm
- Experiments to suppress electron emission
 - Solenoid field
 - Structure of bema duct: Beam duct with ante-chamber
 - Surface with a low SEY

Here the results are briefly reviewed.





• Beam duct with ante-chamber (2003 ~):

- Effective to reduce photoelectrons in beam channel
- Also effective to dilute power density of SR
 - Important for high intensity machines: ex. Super B-factories







• Copper ducts with an antechamber was manufactured

- Installed in the KEKB positron ring
- Eltestrom(persnen)t was measured usinghaaedeetront]





Electron Monitor (DC, Collector:+100 V, Repeller:-30V)





o Electron Monitor

Attached at the bottom of test chamber





- Comparison with simple circular duct.
 - At low current (<100 mA) : Reduction <1/100</p>
 - Photoelectron is well suppressed.
 - At high current (>1500 mA): Reduction by a factor of 4







 Beam duct at wiggler section (2005~)

- A test duct was installed into LER wiggler section.
- Reduction of photoelectrons were confirmed again.





Experiment: Low SEY Surface

• Essential cure at relatively high current

- Surface with a low SEY
- Promising candidates:
 - TiN coating
 - Has long history for various apparatus.
 - NEG coating
 - Developed by CERN and SAES Getters.
 - Has pumping effect.
 - Rough surface (groove)
 - Proposed from BINP and SLAC
 - Intensive R&D is undergoing at SLAC
 - DLC (Graphite)
 - Need further R&D

Y.Suetsugu, et al.,NIM-PR-A, 554 (2005) p.92 Y. Suetsugu,et al;,NIM-PR-A, 556 (2006) p.399

Focused on at KEKB Experiment: Low SEY Surface

- o Our experiment (2004~):
 - Effects of TiN and NEG coatings were examined using the KEKB
- Methodology
 - Test chambers (Cu, TiN-coated and NEG-coated) were installed in the KEKB positron ring.
 - Number of electrons near the beam orbit was measured using an electron monitor, and compared each other.
 - Photoelectron yield and secondary electron yield was estimated using a simulation of electron current.



• Test chambers were installed in arc section.

- Direct SR of 1x10¹⁶ photons/s/m/mA was irradiated at side wall.
- Incident angle ~8 mrad.







- Test chambers were baked before the installation at 150°C for 24 hours.
 - Residual gas components, base pressures were checked.
- NEG-coated chamber was baked in situ after the installation for at 180°C 6 hours followed by at 200°C for 2 hours.
 - Only test chamber
 - No *in situ* baking for TiN-coated chamber





o Vacuum scrubbing



- NEG-coated duct is the lowest among the three surfaces.
 - By a factor of 5 @1E24 compared to copper.
 - Low gas desorption rate, and pumping in itself.
 - But not so prominent as reported so far.

 \leftarrow Only one chamber was baked.

• TiN-coated duct was much higher than copper at first, but by a factor of 2 @1E24.



 Electron currents were measured against beam current in a usual beam operation.

o Aging of SEY by electron bombardment was seen.



Electron Dose : 4x10⁻⁶A/1500mA/40mm² ~ 7x10⁻¹¹C/s/mA/mm² @40 A hours: 7x10⁻¹¹x40000x3600 ~ 1x10⁻²C/mm² =10 mC/mm²



• Cu, TiN, NEG for the same beam condition (After aging)



- *I*_e for NEG coating is almost same as that of Cu, except for high current.
- I for TiN coating is clearly lower than those for Cu and NEG (by factor of 2).
- TiN seems better from the view point of small electron numbers in the beam duct.
- Little difference even after additional baking of NEGcoated chamber at 220°C for 2 hours.



• Dependence on bunch filling pattern

• For every case, $I_e(Cu) \sim I_e(NEG) > I_e(TiN)$



1 RF bucket = 2 ns 1 mA / bunch = 1×10^{-8} C / bunch = 6.2×10^{10} e⁻ / bunch

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• Electron density can be estimated by the electron current at a high repeller voltage. (by K.Kanazawa, KEK)





- Simulation
- o Purpose
 - Understand the behavior of measured electron currents
 - Estimate the SEY (δ_{max}) and PEY (photoelectron yield) of Cu, NEG and TiN.

• Method:

"Macro" electrons (≤10⁴ electrons) are traced from the emission, and the number of electrons hitting the bottom of duct (position of electron monitor) with an almost normal incidence angle are counted.

Emitting point of photoelectrons Position of monitor [Example of electron trajectories (Only photoelectrons, No secondary

electrons, No space charge)]



• Curve fitting by scanning photoelectron yield η_e (0.1 $\leq \eta_e \leq$ 0.4) and Max. SEY δ_{max} (0.8 $\leq \delta_{max} \leq$ 2.0).



- TiN coating seems better from view points of low δ_{max} and small η_e .
- δ_{\max} of NEG is lower than Cu, but not so clear due to high η_e .
- The δ_{\max} of Cu, NEG and TiN is near to those measured in laboratory after sufficient electron bombardment.



• For reference, simulation well explained the dependence on bunch fill pattern.



Experiment: Low SEY Surface



Measurement at a straight section (2006~)

- Very low photons: 1x10¹⁴ photons/s/m/mA (1/100 of arc)
- SR mask shadows the chamber
- Eliminate the effect of SR
- Copper, TiN coating and **NEG** coating (not yet)







• Measured electron current and density



• Electron density for TiN coated duct is about 1/3 ~ 1/4 of that of copper.

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• Measured electron density



• Electron density for TiN coated duct is about 1/3 ~ 1/4 of that of copper.

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• Estimation of δ_{max} by simulation (preliminary)



• Behavior of measured electron current qualitatively corresponds to the simulation curve calucated with δ_{max} 20 btained before. ILCDR06, Cornell University 2



• Estimation of δ_{max} by simulation (preliminary)



o Further simulation is required.





R&D to suppress ECI effect has been performed using KEKB positron ring

- Beam duct with ante-chambers was found to be very effective to reduce photoelectrons, by several orders.
- TiN coating reduce the electron density even at high current, by factors
- TiN coating seems the most promising one at present
- Test of NEG coating duct at straight section is undergoing.

• Next step:

- Combination of TiN (or NEG) coating and a beam duct with antechamber.
- Measurement of electron density in B and Q magnets, and Wiggler.
- Experiment of rough surfaces, and clearing electrode?



o Combination with beam duct with ante-chamber









- The reduction of photoelectrons : 1/60
- Well reproduced the measurement.
- For δ_{max} =1.0-0.9, the electron density in the beam channel should further decrease to 1/2, totally 1/6 1/8 compared to simple circular one.







• Conditions:

- Following CERN method.
- Coated at BINP
- Magnetron discharge
 - P ~ 0.3 Pa (Kr), B ~105 G
 - I = 150 mA, V = 400 V
- Deposition rate = $\sim 1\mu m/12$ hours
- Pre-baking: 24 hours at 250°C
- Temperature is kept at 100°C during coating



Courtesy of A.Krasnov

A chain of collaboration research with BINP





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• Sticking coefficient just after coating for H_2

sample 1 before activation sample 2 before activation

Sample 1 at 300 after 200h

sample 1 at T=255C sample 2 at T=255C sample 2 at T=200C

- 1.4 % (S ~ 0.6 $l/s/cm^2$)
- Composition (by XRF)
- Thickness (by XRF)
 - **0.7 0.9** μ**m**
- Particle size (by XRD)
 - 1.0 1.5 nm (amorphous)

All measured by A.Krasnov.

o SEY









• Conditions:

- Following method for SNS
- Coated at BNL
- Magnetron discharge
 - P ~ 0.6 Pa (Ar+N₂)
 - I ~ 1700 mA, V ~ 380 V
- Deposition rate: ~1 μ m/1 hour
- Pre-baking: 72 hours at 220°C.
- GDC before coating
- Ti underlayer
- Temperature is kept at 220°C during coating

A chain of US-Japan collaboration research







- Thickness (by stylus profiler)
 - **0.3 ~1** μ**m**
- Composition (by AES)
 - Ti:N =49 : 51
- SEY (from data of SNS chamber)
 - δ_{max} =1.6 1.8





Fig. 6 The SEY value vs. primary electron energy of coated samples at 1.5 mTorr (Low P) and 5 mTorr (high P).

H. Hseuh, ECLOUD'04